

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hsiao-Wei Yeh</td> <td>04/27/2007</td> </tr> <tr> <td>Jen-Chieh Shih</td> <td>04/27/2007</td> </tr> <tr> <td>Jian-Hong Chen</td> <td>04/27/2007</td> </tr> </tbody> </table>		Name	Execution Date	Hsiao-Wei Yeh	04/27/2007	Jen-Chieh Shih	04/27/2007	Jian-Hong Chen	04/27/2007
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Hsiao-Wei Yeh	04/27/2007								
Jen-Chieh Shih	04/27/2007								
Jian-Hong Chen	04/27/2007								
RECEIVING PARTY DATA									
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.								
Street Address:	No. 8, Li-Hsin Road 6								
Internal Address:	Science-Based Industrial Park								
City:	Hsin-Chu								
State/Country:	TAIWAN								
Postal Code:	300-77								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11748322</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11748322				
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CORRESPONDENCE DATA									
Fax Number:	(214)200-0853								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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ATTORNEY DOCKET NUMBER:	24061.895								
NAME OF SUBMITTER:	Liem T. Do								

CH \$40.00 11748322

Total Attachments: 2
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source=895Assignment#page2.tif

ASSIGNMENT

WHEREAS, we,

- (1) Hsiao-Wei Yeh of No. 6, Alley 8, Lane 520, Syuefu Rd.
Jhudong Township, Hsinchu County 310, Taiwan, R.O.C.
- (2) Jen-Chieh Shih of 16F, No. 280, Dong Sec. 1, Guangming 6th Rd.
Jhubei City, Hsinchu County 302, Taiwan, R.O.C.
- (3) Jian-Hong Chen of No. 5, Alley 2, Lane 186, Kung-Yuan Rd.
Hsin-Chu, Taiwan, R.O.C.

have invented certain improvements in

MATERIAL AND METHOD FOR PHOTOLITHOGRAPHY

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
 X filed on May 14, 2007 and assigned application number 11/748,322; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C., Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Hsiao-Wei Yeh

Residence Address: No. 6, Alley 8, Lane 520, Syuefu Rd.
Jhudong Township, Hsinchu County 310, Taiwan, R.O.C.

Dated: 2007/4/27

Hsiao-Wei Yeh
Inventor Signature

Inventor Name: Jen-Chieh Shih

Residence Address: 16F, No. 280, Dong Sec. 1, Guangming 6th Rd.
Jhubei City, Hsinchu County 302, Taiwan, R.O.C.

Dated: 2007/4/27

Jen Chieh Shih
Inventor Signature

Inventor Name: Jian-Hong Chen

Residence Address: No. 5, Alley 2, Lane 186, Kung-Yuan Rd.
Hsin-Chu, Taiwan, R.O.C.

Dated: 2007/4/27

Jian-Hong Chen
Inventor Signature